Course Title: Electronic Fabrication
Course Prefix and Number: CETT 1321
Department: Electronics Eng. Tech.
Division: Technology and Business

Course Type: (check one)
- Academic General Education Course (from ACGM – but not in WCJC Core)
- Academic WCJC Core Course
- WECM course (This course is a Special Topics or Unique Needs Course: Y or N)

Semester Credit Hours #: Lecture hours #: Lab/Other Hours #: 3:3:1

EQUITED Pay hours for course: 3.5

Course Catalog Description: A study of electronic circuit fabrication techniques including printed circuit boards, wire wrapping, bread boarding, and various soldering techniques. Skill in techniques of electronic equipment fabrication is gained through layout and construction of a complete unit. Component recognition, schematic symbols, soldering, wire wrapping, ESD considerations, and re-work techniques for discrete, leaded, and surface-mount components. IPC-A-610B training

Prerequisites/Co Requisites: None
I. Topical Outline – Each offering of this course must include the following topics (be sure to include information regarding lab, practicum, clinical or other non-lecture instruction):

**Educational Objectives of CETT1321:**

The following performance will be expected of any student completing this course with a passing grade. There is no absolute time limit on the performance of these objectives, unless noted, but the grade received by the student may depend, in part, on the relative speed and precision of the student’s performance in these tasks.

- Describe some of the factors that are taken into account when one designs electronic equipment.
- Identify components on preliminary sketches and formal drawings of electronic equipment.
- Describe and/or demonstrate safe and proper care and usage of hand tools, power tools, and measuring instruments which are commonly encountered in constructing electronic devices.
- Demonstrate the safe and proper care and usage of chemicals frequently used in electronic device cleaning and construction.
- Demonstrate several of the methods (soldering, crimping, and mechanical) of making electrical connections.
- Demonstrate the fabrication of various types of cables and connectors.
- Produce acceptable solder connections on assigned projects.
- De-solder components from circuit boards without causing any damage.
- Exposure to layout, and fabrication of printed circuit boards.
- Exposure to fabrication and repair techniques of electrical connectors and components.
- Identify electronic components from their schematic symbols.
- Demonstrate ability to correctly mount several types of SMT (Surface Mount Technology) components.
- Complete individual projects as assigned by the instructor.

II. Course Learning Outcomes

<table>
<thead>
<tr>
<th>Learning Outcome</th>
<th>Methods of Assessment</th>
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<tr>
<td>Upon successful completion of this course, students will:</td>
<td>Outcomes 1-6 will be assessed by:</td>
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<tr>
<td>1. Apply electronic circuit fabrication techniques to industry standards</td>
<td>Exams – written, solder projects</td>
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<td>3. Create schematic/wiring diagrams</td>
<td>Labs</td>
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<td>4. Apply circuit description</td>
<td>Quizzes</td>
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<td>5. Identify the tools required to produce a printed circuit board</td>
<td>Reassessed in Capstone Experience: CETT 2349</td>
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<tr>
<td>6. Produce soldering connections.</td>
<td>Final Project course</td>
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III. Required Text(s), Optional Text(s) and/or Materials to be Supplied by Student.

An appropriate electronics text covering fabrication techniques such as Electronic Assembly Concepts and Experimentation, Fredrick Hughes

IV. Suggested Course Maximum – 16
V. List any specific spatial or physical requirements beyond a typical classroom required to teach the course. A laboratory with one workstation per student, equipped with industry-standard soldering and rework equipment. Good lighting and ventilation, and sufficient electrical service.

VI. Course Requirements/Grading System – Describe any course specific requirements such as research papers or reading assignments and the generalized grading format for the course

Evaluation of Performance:
Course grades will be determined by the percentage of course objectives for which the student can demonstrate mastery and by attendance. Mastery of course objectives will be determined by written examinations, physical soldering exams, an attendance grade as described in the Departmental Policy handout, a daily work grade which will include graded homework, graded laboratory work, and a comprehensive final exam.

Approximate Grade Evaluation Summary:

<table>
<thead>
<tr>
<th>Component</th>
<th>Percentage</th>
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<tbody>
<tr>
<td>Major tests</td>
<td>60%</td>
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<tr>
<td>Attendance</td>
<td>10%</td>
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<tr>
<td>Lab reports, homework, and quizzes</td>
<td>15%</td>
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<tr>
<td>Final examination</td>
<td>15%</td>
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Grade Scale:
- 90 to 100: A
- 80 to 89: B
- 70 to 79: C
- 60 to 69: D
- 0 to 59: F

VII. Curriculum Checklist

☐ - Academic General Education Course (from ACGM – but not in WCJC Core)
   No additional documentation needed

☐ - Academic WCJC Core Course
   Attach the Core Curriculum Checklist, including the following:
   - Basic Intellectual Competencies
   - Perspectives
   - Exemplary Educational Objectives

☒ - WECM Courses
   If needed, revise the Program SCANS Matrix & Competencies Checklist